

## -3.8A, -30V P-Channel Power MOSFET

### GENERAL DESCRIPTION

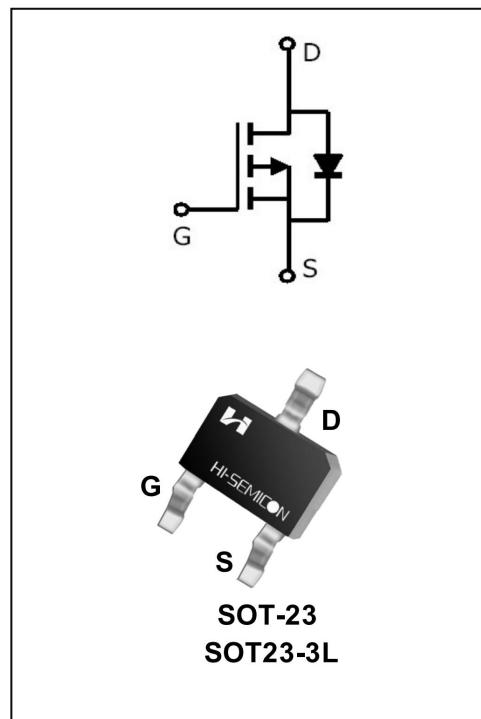
The Power MOSFET has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

### Features

- ◆  $V_{DS} = -30V$ ,  $I_D = -3.8A$
- ◆  $R_{DS(ON)}$   
TYP:  $59m\Omega @ V_{GS} = -10V$

### Applications

- ◆ Power factor correction (PFC)
- ◆ Switched mode power supplies (SMPS)
- ◆ Uninterruptible power supply (UPS)
- ◆ LED lighting power



### ORDERING INFORMATION

Part No.	Package	Marking	Material	Packing
SFS2303	SOT-23 SOT23-3L	2303	Pb Free	Reel

ABSOLUTE MAXIMUM RATINGS ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Characteristics	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Drain Current	$I_D$	-3.8	A
		-2.5	
Drain Current Pulsed (Note 1)	$I_{DM}$	-12	
Power Dissipation( $T_C=25^\circ\text{C}$ ) -Derate above $25^\circ\text{C}$	$P_D$	1.0	W
Operation Junction Temperature Range	$T_J$	-55~+150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55~+150	
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	$TL$	300	

## ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain -Source Breakdown Voltage	$B_{VDSS}$	$V_{GS}= 0\text{V}, I_D= -250\mu\text{A}$	-30	--	--	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}= -30\text{V}, V_{GS}= 0\text{V}$	--	--	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}= 20\text{V}, V_{DS}= 0\text{V}$	--	--	100	nA
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}= -20\text{V}, V_{DS}= 0\text{V}$	--	--	-100	
On Characteristics						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}= V_{DS}, I_D= -250\mu\text{A}$	-1.0	1.9	-2.5	V
Static Drain- Source On State Resistance	$R_{DS(on)}$	$V_{GS}= -10\text{V}, I_D= -2.5\text{A}$	--	59	75	$\text{m}\Omega$
		$V_{GS}= -4.5\text{V}, I_D= -2.5\text{A}$	--	103	120	
Dynamic Characteristics						
Input Capacitance	$C_{iss}$	$V_{DS}= -15\text{V}$ $V_{GS}= 0\text{V}$ $f=1.0\text{MHz}$	--	285	--	pF
Output Capacitance	$C_{oss}$		--	49	--	
Reverse Transfer Capacitance	$C_{rss}$		--	32	--	
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}= -15\text{V}, V_{GS}= -10\text{V}$ $R_G= 6\Omega, I_D= -3.0\text{A}$ (Note 2.3)	--	12.5	--	nS
Turn-on Rise Time	$t_r$		--	10.8	--	
Turn-off Delay Time	$t_{d(off)}$		--	21.5	--	
Turn-off Fall Time	$t_f$		--	7.1	--	
Total Gate Charge	$Q_g$	$V_{DS}=-15\text{V}, I_D=-3.0\text{A}$ $V_{GS}=-10\text{V}$ (Note 2.3)	--	9.1	--	nC
Gate-Source Charge	$Q_{gs}$		--	2.6	--	
Gate-Drain Charge	$Q_{gd}$		--	1.8	--	

## SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	$I_S$	Integral Reverse P-N Junction Diode in the MOSFET	--	--	-3.8	A
Pulsed Source Current	$I_{SM}$		--	--	-12	
Diode Forward Voltage	$V_{SD}$	$I_S = -2A, V_{GS} = 0V$	--	-0.8	-1.2	V

## NOTE:

1.Pulse width limited by maximum junction temperature

2.Pulse Test: Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$

3.Essentially independent of operating temperature



## Typical Performance Characteristics

Figure 1. Output Characteristics

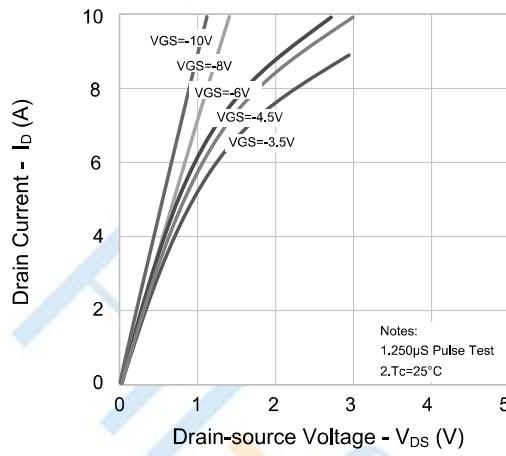


Figure 2. Transfer Characteristics

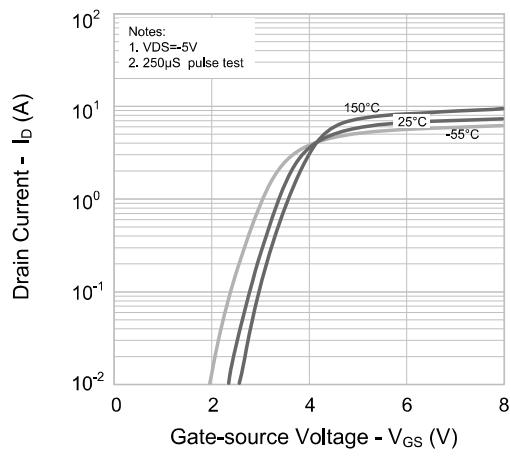


Figure 3. On-resistance vs. Drain Current

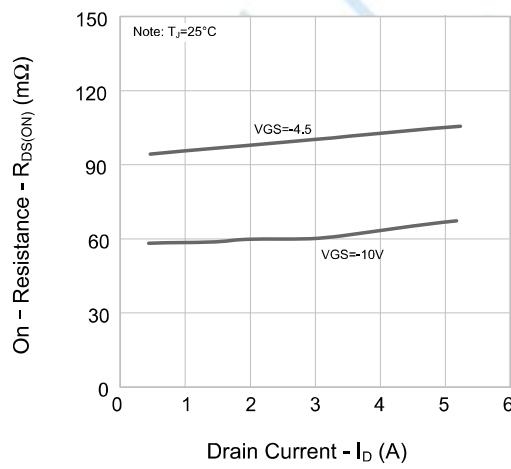


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

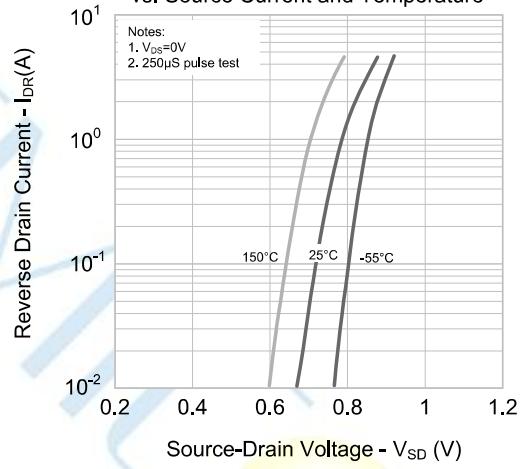


Figure 5. Capacitance Characteristics

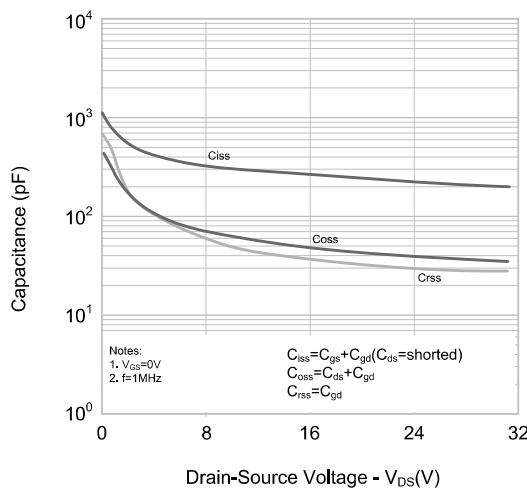
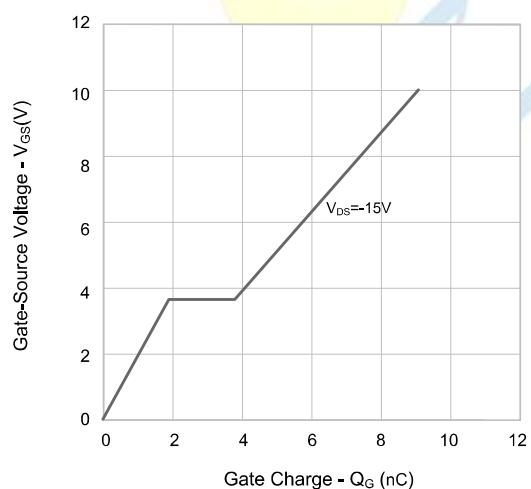
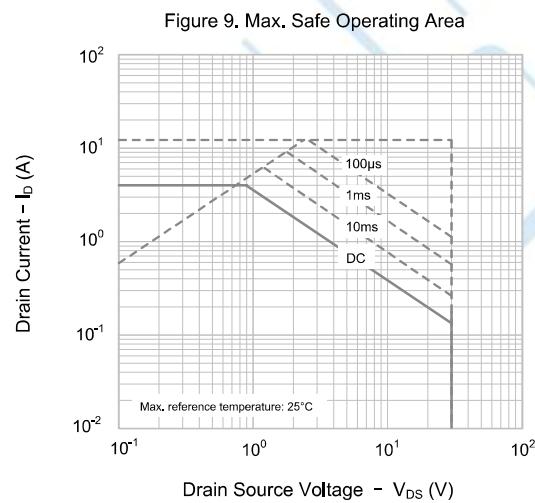
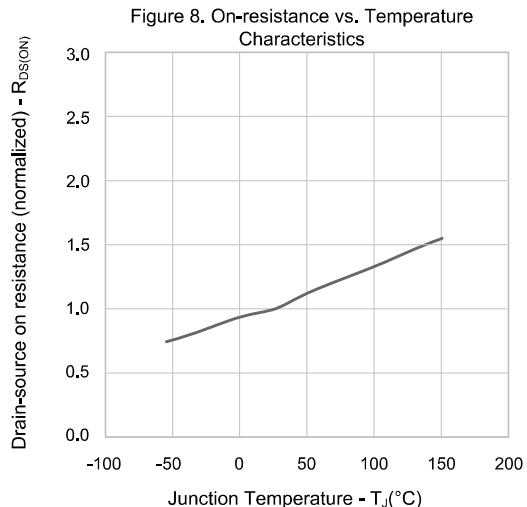
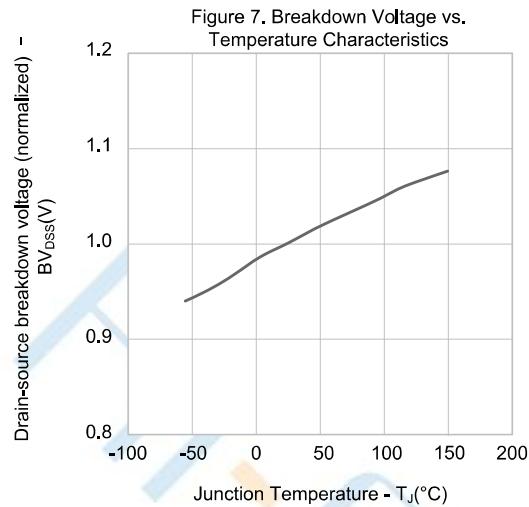


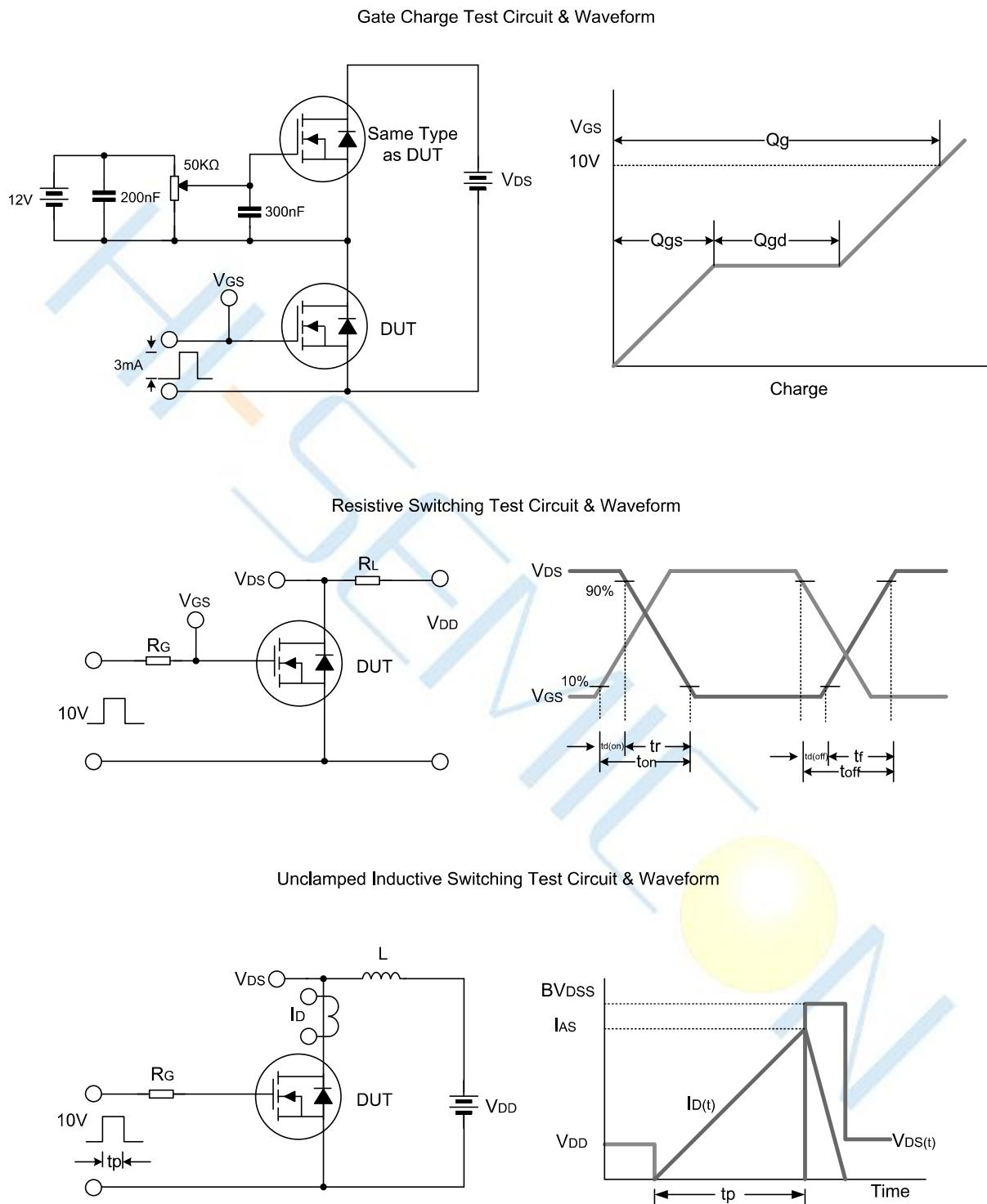
Figure 6. Gate Charge



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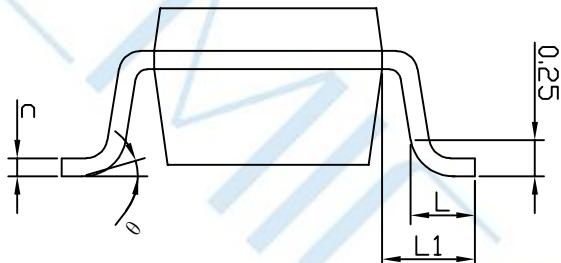
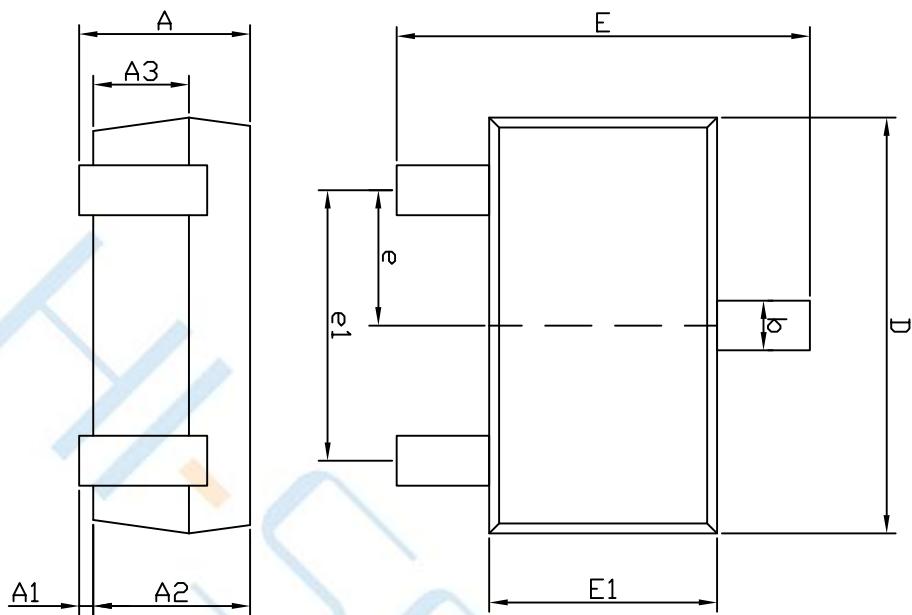


## Test Circuit



## Package Dimensions of SOT23-3L

Unit:mm

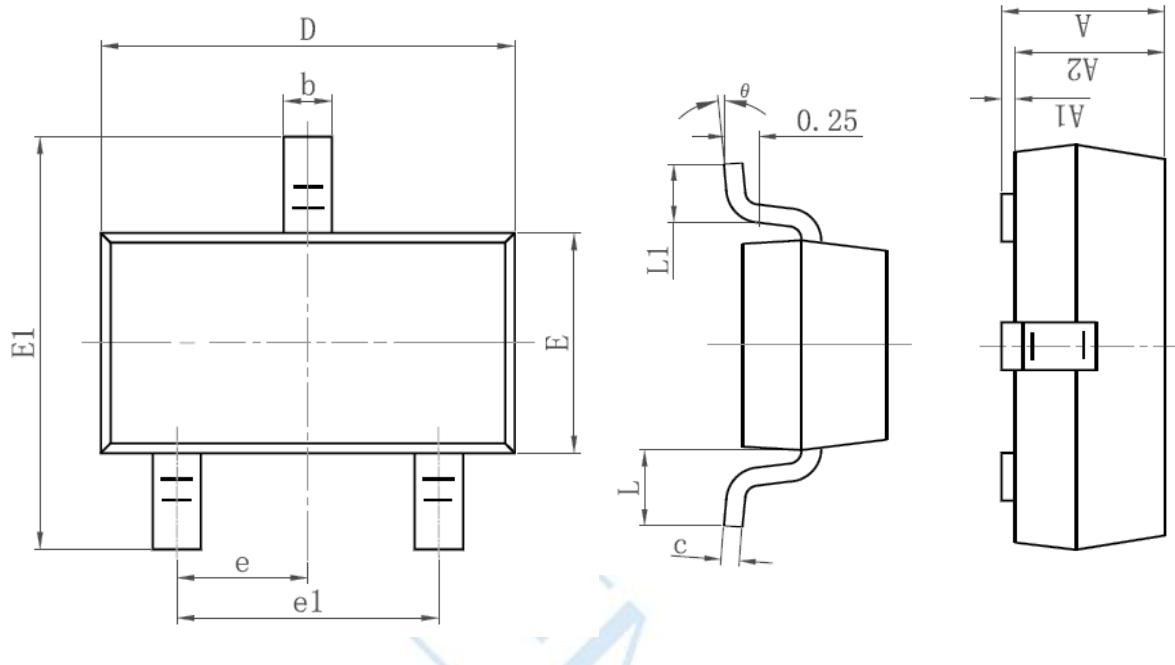


COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	-	-	1.25
A1	0.04	-	0.10
A2	1.00	1.10	1.20
A3	0.60	0.65	0.70
b	0.33	-	0.41
c	0.11	-	0.20
D	2.82	2.92	3.02
E	2.60	2.80	3.00
E1	1.50	1.60	1.70
e	0.95BSC		
e1	1.90BSC		
L	0.30	-	0.60
L1	0.60REF		
$\theta$	0°	-	8°

## Package Dimensions of SOT-23

Unit:mm



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

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